



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Reissue Application of: Heppler

Serial No.: 08/715,869

Filed: September 19, 1996

Title: METHOD AND APPARATUS FOR
TESTING INTEGRATED CIRCUITS

Examiner: T. Nguyen

Group Art Unit: 3615

Attorney Docket No.: 2972US (92-0476RE)

CERTIFICATE OF MAILING

I hereby certify that this paper or fee along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

October 5, 1998
Date of Deposit

Darlene Foucault
Signature of registered practitioner or other
person having reasonable basis to expect mailing
to occur on date of deposit shown pursuant to 37
C.F.R. § 1.8(a)(1)(ii)

Darlene Foucault
Typed/printed name of person whose signature is
contained above

11:11 AM 11/15/98
U.S. PATENT & TRADEMARK OFFICE
MAILING SYSTEM

RESPONSE TO FIRST OFFICE ACTION

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action mailed July 9, 1998, please amend the application as follows:

IN THE SPECIFICATION

In column 1, please change the paragraph in lines 14-34 to read as follows:

FIG. 1 illustrates a representative portion of a semiconductor chip trim and pin forming machine. One can purchase such a machine from ASM Asia Inc., 4302 E. Broadway Rd., Phoenix, Ariz., model AP50, or from Precision Technologies Inc. 1725 De La Cruz Blvd. #4, Santa Clara, Calif. 95050, models Matrix SS, FS, or FM. FIG. 1 identifies the following elements: Platen 40 is the portion of the press-type machine to moved up and down to stamp in the desired forming and trimming operations. Vertical action rod 42 is attached to a means for moving platen 40 into contact with the non movable table 44. IC forming and cutting die [44] 45 are mounted to both the platen 40 and table 44. IC loading station 50 receives a set of ICs usually from the plastic encapsulation station and they are attached on a typical single leadframe. Trim stations 60 will trim off the excess encapsulation material and metal leadframe portions. Forming stations 70 will bend the leads of the ICs into various configurations like "SOJ" or DIP.